



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR MINI QFN-6L

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
85/85	165	27,720	85 °C, 85 % RH	0	0.00
BOND INT	80	40,000	200 °C + N2	0	0.00
HAST	165	16,500	130 °C, 85 % RH	0	0.00
Pressure Pot	165	15,840	121°, 15 PSIG	0	0.00
Solder DUNK	55	165	260 °C, 10 SEC	0	0.00
Temp Cycle	165	82,500	- 65 °C to 150 °C	0	0.00